

CRMQGL1012A N-Channel 100V, 10mΩ Typ. Power MOSFET

Description



• 100V, 50A

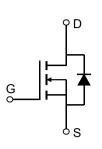
 $R_{DS(ON)}$ Typ = 10m Ω @ V_{GS} = 10V

 $R_{DS(ON)}$ Typ = 13m Ω @ V_{GS} = 4.5V

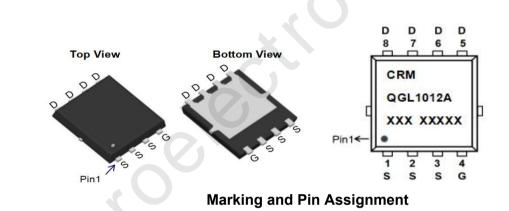
- Advanced Split Gate Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- Lead Free
- 100% UIS TESTED!
- 100% ΔVds TESTED!

Application

- Load Switch
- PWM Application
- Power Management



Schematic Diagram



Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMQGL1012A	CRMQGL1012A	PDFN3.3x3.3-8L	TAPING	13"	5000	50000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		100	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	$T_c = 25^{\circ}C$	50	А
I _D		T _C = 100°C	30	А
I _{DM}	Pulsed Drain Current ⁽¹⁾		200	А
E _{AS}	Single Pulsed Avalanche Energy ⁽²⁾		56	mJ
P _D	Power Dissipation	T _c = 25°C	56	W
$R_{ extsf{ heta}JC}$	Thermal Resistance, Junction to Case		2.2	°C/W
Τ _J , Τ _{stg}	Junction & Storage Temperature Range		-55 to 150	°C



Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Chara	acteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics					
V _{GS(th)}	Gate Threshold Voltage	V_{DS} = V_{GS} , I_D = 250 μ A	1	1.7	2.5	V
_	(2)	V _{GS} = 10V, I _D = 30A	-	10	13	mΩ
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 4.5V, I _D = 25A	-	13	17	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance		-	1500	-	pF
C _{oss}	Output Capacitance	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz	-	840	-	pF
C _{rss}	Reverse Transfer Capacitance			30	-	pF
Q _g	Total Gate Charge		<u> </u>	35	-	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0$ to 10V $V_{DS} = 50V$, $I_{D} = 15A$	-	4.5	-	nC
Q_{gd}	Gate Drain("Miller") Charge	$v_{\rm DS} = 50$ v, $I_{\rm D} = 15$ A	-	8	-	nC
Switchin	g Characteristics					
t _{d(on)}	Turn-On DelayTime		-	16	-	ns
t _r	Turn-On Rise Time	V _{GS} = 10V, V _{DD} =50V	-	13	-	ns
$t_{d(off)}$	Turn-Off DelayTime	I_D = 15A, R_{GEN} = 3 Ω	-	37	-	ns
t _f	Turn-Off Fall Time		-	17	-	ns
Drain-So	urce Diode Characteristics and M	lax Ratings				
I _s	Maximum Continuous Drain to Source Di	ode Forward Current	-	-	50	А
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	200	А
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	38	-	ns
Qrr	Body Diode Reverse Recovery Charge	I _F = 12A, di/dt = 100A/us	-	35	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. E_{AS} condition: Starting T_J=25C, V_{DD}=50V, V_G=10V, R_G=250hm, L=0.5mH, I_{AS}=15A

3. Pulse Test: Pulse Width ${\leqslant}300\mu s,$ Duty Cycle ${\leqslant}0.5\%.$



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Test Circuit

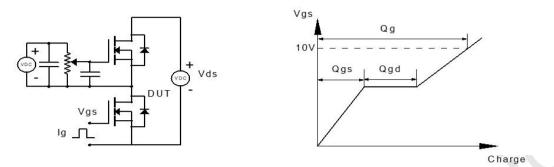


Figure 1: Gate Charge Test Circuit & Waveform

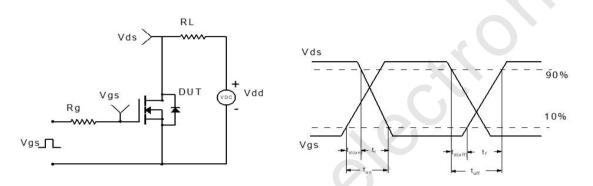


Figure 2: Resistive Switching Test Circuit & Waveform

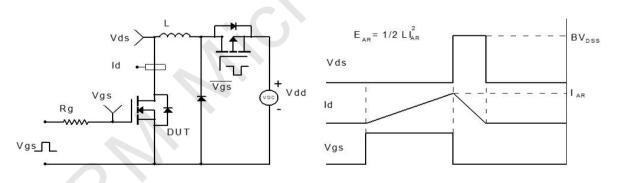
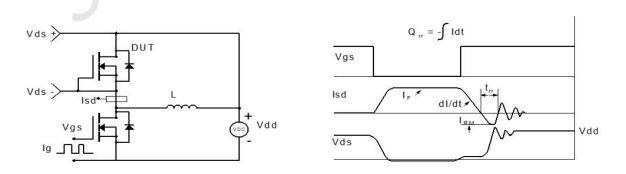


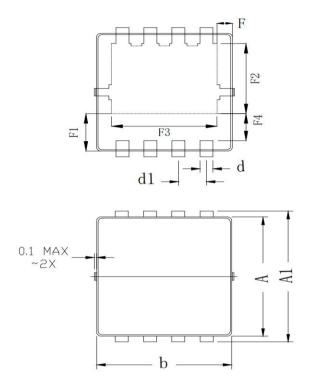
Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

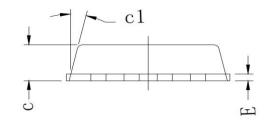






Package Mechanical Data(PDFN3.3x3.3-8L)





	COMMON DIN	IENSION (MM)	
PKG	PDFN 3.3×3.3-8L		
SYMBOL	MIN	TYP	MAX
A	3.070	3.100	3.130
A1	3.300	3.400	3. 500
b	3.070	3.100	3.130
С	0.770	0.800	0.830
c1		13°	
d	0.275	0.300	0. 325
d1	0.625	0.650	0.675
E	0.144	0.152	0. 160
F	0.300	0. 325	0.350
F1	0.960	0.985	1.010
F2	1.775	1.800	1.825
F3	2.425	2.450	2.475
F4	0.660	0.685	0.710

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